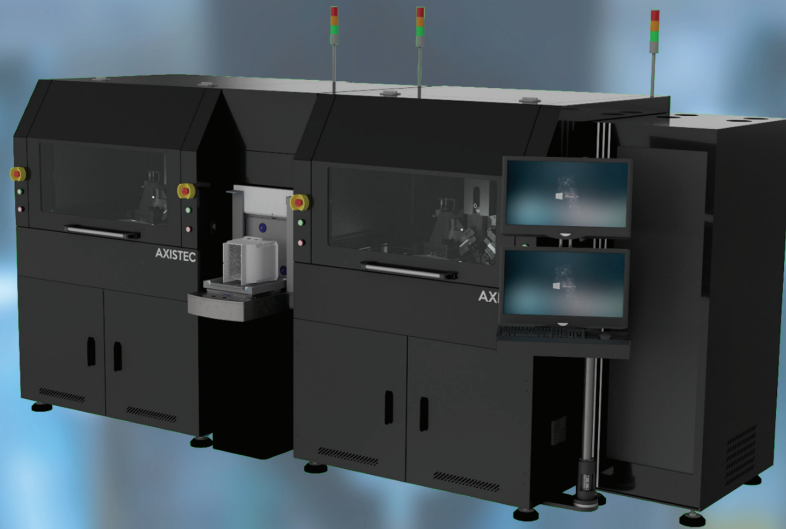


actif

SILICON PHOTONICS WAFER LEVEL TESTER



BENEFITS & FEATURES

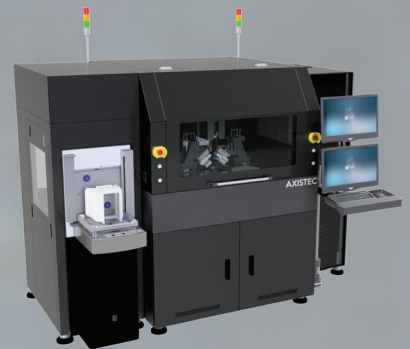
- High Speed Fiber / Fiber Array Alignment
 - ♦ <3 seconds for single alignment
 - ♦ <1dB insertion loss
- Precision Handling System
 - ♦ Vision alignment in multiple dimensions
 - ♦ 6 Axis of freedom probers
- High Integration Flexibility
 - ♦ Integrated to various test equipment
 - ♦ Expandable to any communication protocol
- Low Cost Capital Investments
 - ♦ Competitive Price offer Shorter ROIs

**"SMART AUTOMATION
FOR INNOVATORS"**

A FULLY AUTOMATED SiPH WAFER LEVEL TESTER

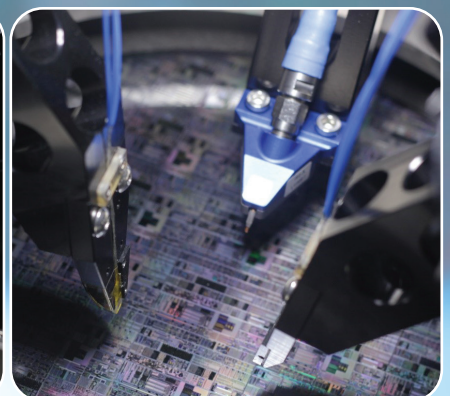
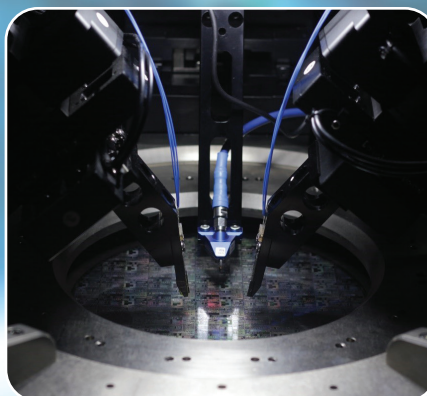
A new generation that supports multiple-wafer tests with faster scanning and shorter test time, Axis-Tec has developed a SiPh Fully Automated Wafer Level Tester with feature-rich capabilities that is mass production ready to determine defective parts and screen for infant mortalities.

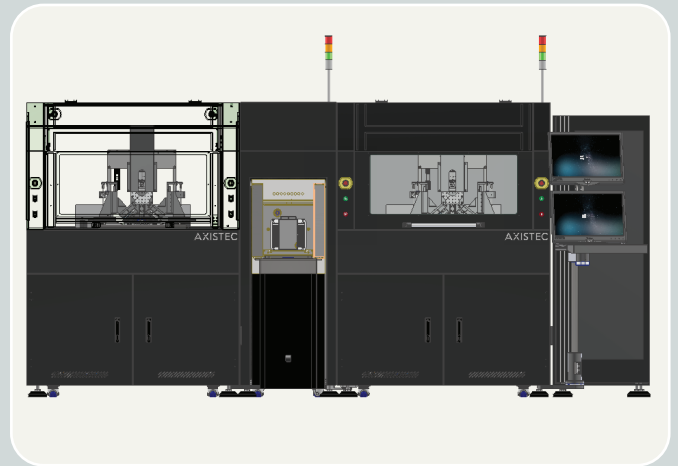
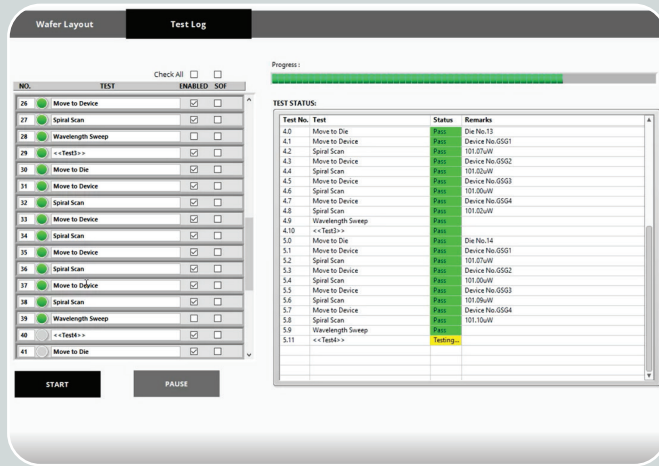
Axis-Tec's Forefront Automated Wafer Level Tester actif comes with all the built-in features and has high flexibilities that can be integrated with a wide range of optical electrical test instruments or equipment to execute testing applications of O-O (Optical to Optical, E-O (Electrical to Optical) and O-E (Optical to Electrical). The wafer level tester is designed and built with automated passive and active align to enable precise optical peak search and electrical probing positioning.



AXISTEC

A subsidiary of Ellipsiz Ltd, a SGX listed company.





GENERAL SPECIFICATIONS

Dimensions

Size: 1.0m x 1.8m x 1.8m (H)
Weight: 500kg

Electrical

220 VAC, 3 kW

Air Supply

500 kPa

Others

Double Vibration Isolation
Cleanroom Compliant

MECHANICAL SPECIFICATIONS

Wafer Chuck Unit

Size: 205 mm (8 inch)
Plating: Nickel
Travel X: 300 mm
Travel Y: 700 mm
Resolution X,Y: 0.05 μ m
Repeatability: $\leq 1 \mu$ m
Speed: Max 500 mm/s
Travel Z: 20 mm
Resolution: 0.1 μ m
Repeatability: $\leq 2 \mu$ m
Speed: Max 10 mm/s
Rotary (θ): 360 $^{\circ}$
Resolution: $\leq 0.005^{\circ}$
Repeatability: $\leq \pm 0.01^{\circ}$
Speed: 2 $^{\circ}$ /s

MECHANICAL SPECIFICATIONS

AXIS-A6: 6 Axis motion optical probe module. (XYZ $\theta\phi\psi$)

Travel (X,Y,Z): 50mm
Resolution: 0.05 μ m
Repeatability: $\leq 1 \mu$ m
Speed: 50mm/s
Rotary ($\theta\phi\psi$): $\pm 4^{\circ}$
Resolution: $\leq 0.002^{\circ}$
Repeatability: $\leq \pm 0.01^{\circ}$
Speed: 2 $^{\circ}$ /s

AXIS-A3: 3 Axis motion electrical probe module. (XYZ)

Travel (X,Y,Z): 50mm
Resolution: 0.1 μ m
Repeatability: $\leq 1 \mu$ m
Speed: 50mm/s

APPLICATION SOFTWARE

Modular software architecture promotes high flexibility in creating customised production sequence.

Supports customer test program plug-ins: LabView, TestStand, C#, Python

Auto height compensation

Flexible wafer/device mapping creation

Supports various test instrument integration

AX-PSA: Proprietary on-the-fly peak

VISION SPECIFICATIONS

Camera

Resolution: 12M
Zoom: 12X
FOV Max: 15 x 15 mm
FOV Min: 2 x 2 mm
Travel: 20mm
Height Compensation: $\leq 10 \mu$ m

